

Claims:

1. Copper alloy foil for lamination with a resin substrate, the copper alloy foil consisting essentially of at least one of 0.01 - 2.0 weight percent Cr and 0.01 - 1.0 weight percent Zr, the balance copper and unavoidable impurities, the copper alloy foil having an anticorrosive coating of thickness less than 3 nm, the copper alloy foil having a surface exhibiting no artificial roughening and having a surface roughness less than 2 μm expressed as ten-point average surface roughness, tensile strength greater than 600 N/mm² and conductivity greater than 60% IACS, and 180° peel strength between the copper alloy foil and an adhesive containing an epoxy resin bonding the copper alloy foil to a resin substrate is greater than 8.0 N/cm.

2. Copper alloy foil for lamination with a resin substrate, the copper alloy foil consisting essentially of 1.0-4.8 weight percent Ni, 0.1-1.4 weight percent Si, the balance copper and unavoidable impurities, the copper alloy foil having an anticorrosive coating of thickness less than 3 nm, the copper alloy foil having a surface exhibiting no artificial roughening and having a surface roughness less than 2 μm expressed as ten-point average surface roughness, tensile strength greater than 650 N/mm² and conductivity greater than 40% IACS, and 180° peel strength between the copper alloy foil and an adhesive containing an epoxy resin bonding the copper alloy foil to a resin substrate is greater than 8.0 N/cm.

3. Copper alloy foil according to claim 1 or 2, wherein the anticorrosive coating comprises at least one nitrogen-containing organic compound which forms a chelate with the copper.

4. Copper alloy foil according to claim 1 or 2, wherein the organic compound is selected from the group consisting of benzotriazole and imidazole.

5. Copper alloy foil according to claim 1 or 2, wherein the resin of the resin foil is a polyimide.

6. A laminate comprising a copper alloy foil according to claim 1 or 2 laminated with a resin substrate.

7. The laminate of claim 6, further comprising a resin-containing adhesive bonding the copper alloy foil to the resin substrate.

8. The laminate of claim 7, wherein the resin of the resin-containing adhesive comprises an epoxy.